

PC 600

Pulse Plating Electrolytic Copper Metallization

A Versatile Workhorse Pulse Plating System Used by Manufacturers Worldwide

When it comes to range of applications, uniformity of thickness distribution, and high productivity, the **PC 600** pulse plating acid copper system is the process of choice for fabricators worldwide.

A two-component system, which is easily analyzed by CVS and controlled through auto-dosing, PC 600 is unmatched in its combination of throwing power, microdistribution and high production speeds. Capable of plating on board designs up to and beyond 30:1 aspect ratio, it can be operated in vertical and horizontal plating lines while producing consistently excellent electrolytic copper deposits with high tensile and elongation over a long bath life. PC 600 is the pulse plating metallization used when plating high aspect ratio through holes and microvias by panel, pattern and button plating.

KEY FEATURES

- Extremely wide range of applications
- High throwing power on through holes beyond 30:1 aspect ratio
- High volume production with lowest cost of ownership
- High degree of uniformity for better line widths and spaces
- Compatible with vertical or horizontal equipment
- Two component system is easily analyzable
- Excellent copper deposit properties
- Stable, dependable performance over long bath life



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The Ultimate Combination of Speed, Quality and Reliability

PC 600 brings fabricators the high plating speeds of a pulse plating metallization without cutting back on quality or device reliability.

With excellent physical properties, the deposit produced from the PC 600 bath provides interconnect stress performance which does not degrade as organics build up during the course of operation.

IST Testing Data

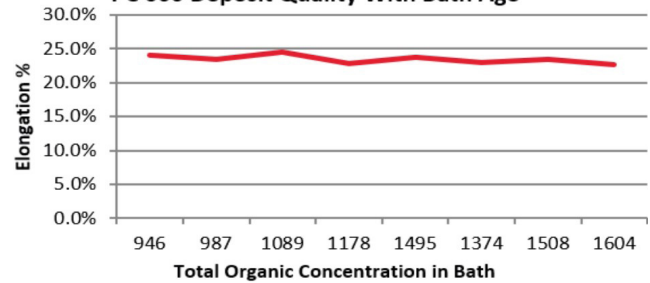
AmpHr/L (10x)	v	7.4	10.3	14.0	28.4	30.4	50	63
Brightener (mL/L)	1.87	1.73	1.94	1.74	1.67	1.81	1.73	1.69
Carrier (mL/L)	36.48	35.78	36.89	35.78	38.42	36.44	35.48	35.94
TOC (ppm)	946	987	1089	1178	1495	1374	1508	1604
9.1mm/0.45mm 20:1 AR	>500	>500	>500	>500	>500	>500	>500	>500
9.1mm/0.55mm 17:1 AR	>500	>500	>500	>500	>500	>500	>500	>500
3.2mm/0.25mm 13:1 AR	>500	>500	>500	>500	>500	>500	>500	>500

Tensile and Elongation %

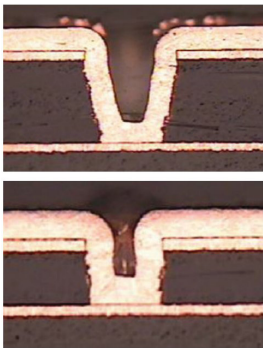
Global Data (n ~ 100)	Tensile (psi)	Elongation (%)
Average	41,806	27.5
Std.Dev.	4,671	4.5

Low statistical variation across more than one hundred installs.

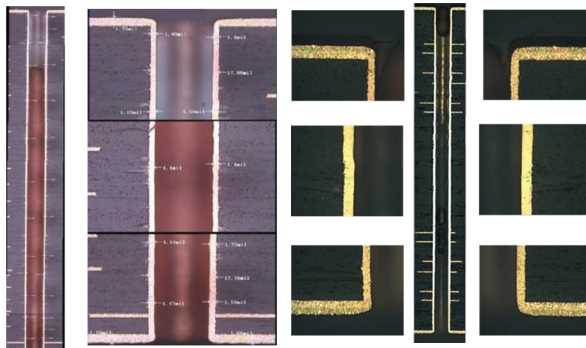
PC 600 Deposit Quality With Bath Age



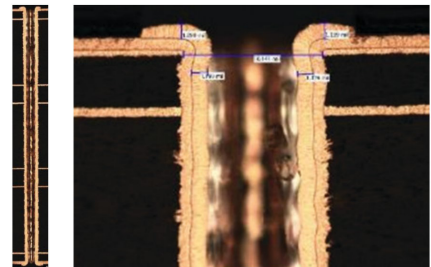
A Huge Range of Board Types, Thicknesses and Dimensions



Microvias



Various Types of High Aspect Ratio Through Holes



Button Plating

